



Material Content Data Sheet



Sales Product Name		BSC009NE2LS		Issued		29. August 2013		
MA#		MA001010850						
Package		PG-TDSON-8-7		Weight*		118.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.009	0.85	0.85	8486	8486
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.74	31.78	317474	317887
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	374	374
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		729	
	plastics	epoxy resin	-	6.156	5.18		51759	
	inorganic material	silicondioxide	60676-86-0	37.112	31.20	36.45	312009	364497
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12204	12204
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1392	1392
solder	non noble metal	tin	7440-31-5	0.029	0.02		244	
	noble metal	silver	7440-22-4	0.036	0.03		305	
	non noble metal	lead	7439-92-1	1.387	1.17	1.22	11660	12209
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.52	9.53	95171	95295
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.74	18.77	187412	187656
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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